



Materials Analysis Technology Inc.

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Independent/Professional Analysis Lab, the best partner to your R&D group!!
Your first choice to product development, quality assurance and IP strategy!!!

Automatic, Ultrasonic AI Wedge Bonder

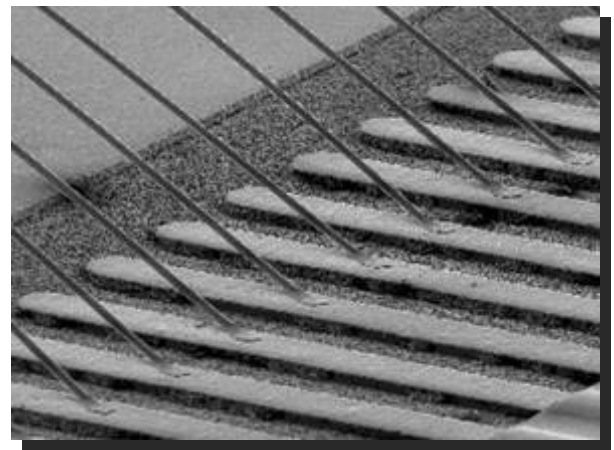
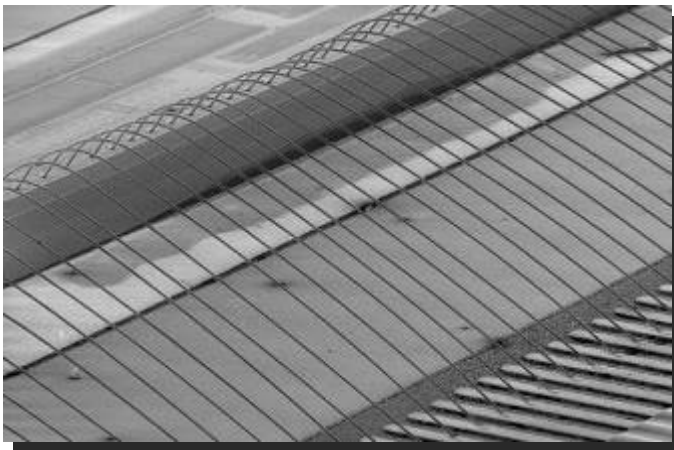


Applications :

- ✓ Chip-on-board, COB, bonding
- ✓ Stacked dice / Multi PCB
- ✓ High lead counts
- ✓ Electroless Ni/Au, ENIG
- ✓ Re-bonding of COF and COG

We provide :

- ✓ High quality and stable bonding services
- ✓ Fast cycle time : < 3 working days delivery
- ✓ Flexibility to meet customer requests
- ✓ Total solutions: die saw, die mount, Al/Au wire-bonding, pull/shear test, fast packaging, SAT / X-ray inspection, electrical verification, etc.



Case Log-in, please call:

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You are highly welcome to use Fedex (account no. 2665-9953-6) , DHL (account no. 968368648) or UPS services for sample shipping. MA-tek will pay the courier charge upon sample arrival.



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